

In the Claims:

Please cancel without prejudice claims 1 to 11 and add the following claims 12 to 20:

A5
~~12~~. In a substrate and layer sequence built on said substrate in thin-film technology, said layer sequence comprising an electrically conductive sputtered layer, an electrically conductive reinforcing layer provided on the sputtered layer to reinforce or strengthen the sputtered layer and at least one electronic component, said reinforcing layer being provided by a method other than sputtering and material being removed from regions of said sputtered layer and said reinforcing layer by means of laser erosion in order to perform an electronic adjustment of said at least one electronic component, said laser erosion producing contaminating conductive deposits on said layer sequence, the improvement characterized by at least partially eliminating said electrically conductive reinforcing layer from said regions prior to said laser erosion;

whereby said contaminating conductive deposits produced by said laser erosion are at least partially eliminated.

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~~18~~. The improvement as defined in claim ~~12~~¹, wherein said electrically conductive reinforcing layer is formed with a smaller thickness in said regions than outside of said regions.

³
~~14~~. The improvement as defined in claim ~~12~~¹, wherein said electrically conductive reinforcing layer is formed so that said reinforcing layer does not cover or extend over said sputtering layer in said regions.

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~~15~~. The improvement as defined in claim ~~12~~¹, wherein a resistor layer is provided between said electrically conductive sputtered layer and said substrate and said electrically conductive reinforcing layer is provided on a side of said electrically conductive sputtered layer opposite from said resistor layer.

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~~16~~. The improvement as defined in claim ~~12~~¹, ~~13~~², ~~14~~³ or ~~15~~⁴, wherein said electrically conductive sputtered layer consists of gold.

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~~17~~. The improvement as defined in claim ~~12~~¹, ~~13~~², ~~14~~³ or ~~15~~⁴, wherein said electrically conductive reinforcing layer consists of gold.

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~~18~~. The improvement as defined in claim ~~12~~¹, ~~13~~² or ~~14~~³, wherein said regions are located in portions of said layer sequence carrying less current than other portions.

⁸
~~19~~. The improvement as defined in claim ~~12~~¹, ~~13~~² or ~~14~~³, wherein at least one of said regions is located at an end of an open strip line.

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